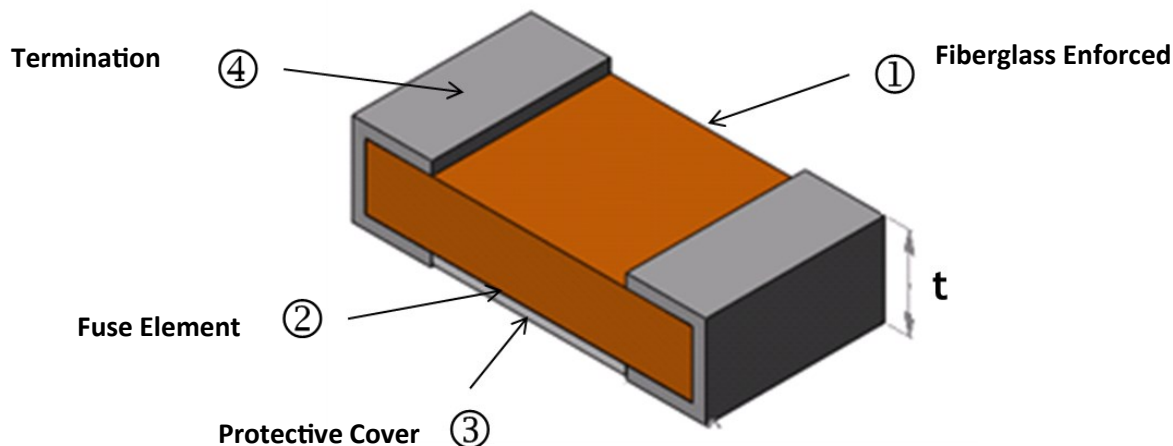


## AEM Components\_Technology Platform

### TF-Fuse<sup>®</sup> Surface Mount Chip Fuses



### Low Profile TF-FUSE<sup>®</sup> with Superior Performance



With patent technology and by integrating the advanced thin film technology, AEM thin film fuses offer a fusing characteristic from very fast acting to high in-rush current. The fiberglass enforced epoxy fuse body and bi-metal fuse element make fuse to provide protection at low fusing temperature.

#### TF-FUSE<sup>®</sup> Features:

- Low rating current capability (from 150mA to 5A)
- Low DCR
- Low fusing ratio
- Low fusing temperature
- Low profile (thickness ~ 0.3mm)
- Small case size (EIA 0402 & 0603)

#### TF-FUSE<sup>®</sup> Applications:

- Notebook computers and tablets
- Memory cards, HDD
- Toys
- Portable electronic devices
- Panels
- Battery pack